# Product End-of-Life Disassembly Instructions

**Product Category:** External Options  

**Marketing Name / Model**  
[List multiple models if applicable.]

**HP Spectre Folio Convertible**

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[]”): [ ] screws [ ] snaps [x] adhesive [ ] other. Explain [ ]</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors/Condensers measuring greater</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

EL-MF877-00  
Template Revision C  

Last revalidation date 09-May-2018  

HPI instructions for this template are available at [EL-MF877-01](#)
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords/Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**2.0 Tools Required**

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

**Tool Description**

**Specifications:**

- working mat of the heating mat: L:30.5mmxW:20.2mm(W=10mm)
- dimensions of the device: (L) 27.5mm x (W) 24.5(36)mm x (H)28.5mm
- Semi-automatic separation mode: 55°C / 5 min (with adjustable temperature and time)
- Semi-automatic temperature support mode: 55°C (with adjustable)
- temperature range: 50~55°C
- Power: 100W(220V)
- Weight: about 19.6kg

**Description #2**

<table>
<thead>
<tr>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philip #1 / TORX T</td>
</tr>
</tbody>
</table>

**3.0 Product Disassembly Process**

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:
1. De-bonding Glass + LCM.
2. Cut off power by shipping mode switch, and release cables (WWAN/WLAN/e-DP/Antenna/Camera…).
3. Disassembly WWAN PCB/Module/ IR-camera bracket.
4. Disassembly fixture screw between LCD COVER & Inner TOP.
5. Disassembly fixture screw between Hinge Arm top & Inner BTM.
6. Disassembly LCD ASSY/KB-Deck and leather unit (/s battery & TP module).
7. Disassembly SPK Box(/s driver & WiFi module) from KB-Deck..
8. Disassembly LCD ASSY & KB-Deck(/s MB)
9. Disassembly HINGE base on KB-Deck.
10. Disassembly MB/SSD module on KB-Deck.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

**Step 1 De-bonding Glass + LCM.**

**Step 2 Cut off power and release cables.**
Step 3 Disassembly WWAN PCB/Module/IR-camera bracket.
Step 4 Disassembly fixture screw between LCD COVER & Inner TOP.

**LCD side:**

- **a.** Release leather up side.
- **b.** Lift up LCD COVER to reveal fixtured screw on HINGE ARM TOP*10pcs.

**Step 5** Disassembly fixture screw between Hinge Arm top & Inner BTM.

- **Leather side:**

- **a.** Release logic screw rubber *7pcs.
- **b.** Slide out KB-Deck.
- **c.** Lift up KB-Deck to reveal MB.
- **d.** Then to release Battery connector / TP connector to cut off logic up and leather unit connection.

**Step 6** Disassembly LCD ASSY/KB-Deck and leather unit (/s battery & TP module).

HPI instructions for this template are available at [EL-MF877-01](http://EL-MF877-01)
Step 7 Disassembly SPK Box (/s driver & WIFI module) from KB-Deck.

a. To release e-DP /WWAN/WLAN cable connector, WIFI cable connector, SPK connector.
Step 8 Disassembly LCD ASSY & KB-Deck (/s MB).
Step 9 Disassembly HINGE base on KB-Deck.

Step 10 Disassembly MB/SSD module on KB-Deck.